

LNJ837W83RA

High Bright Surface Mounting Chip LED

ESS II Type

Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	55	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

Lighting Color

- Orange

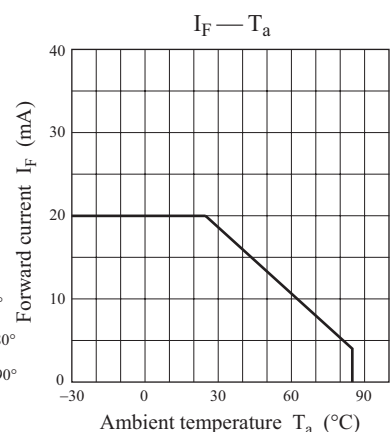
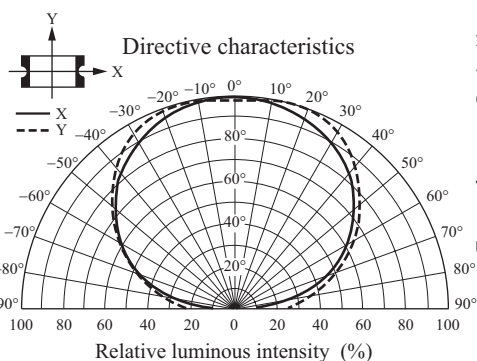
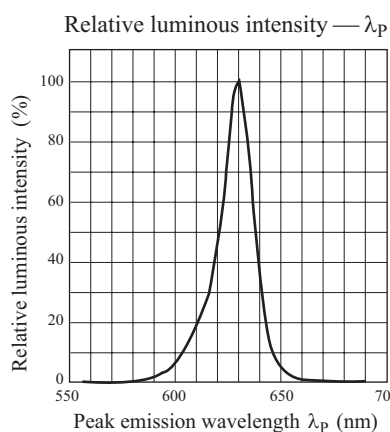
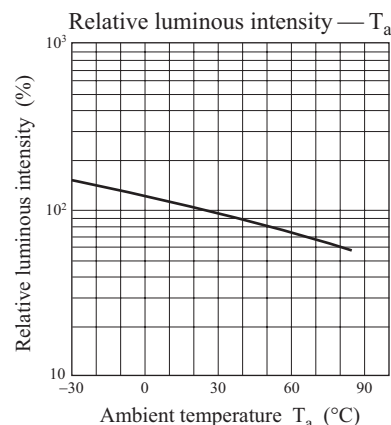
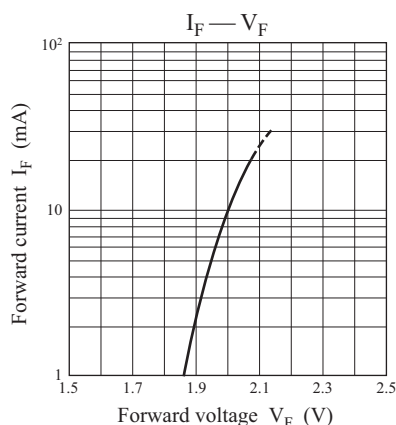
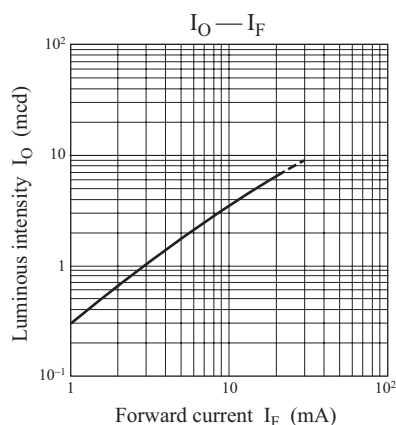
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

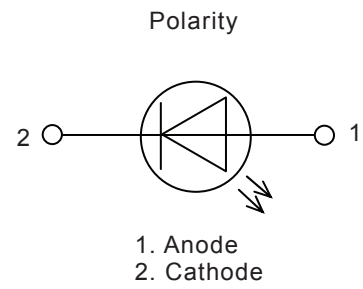
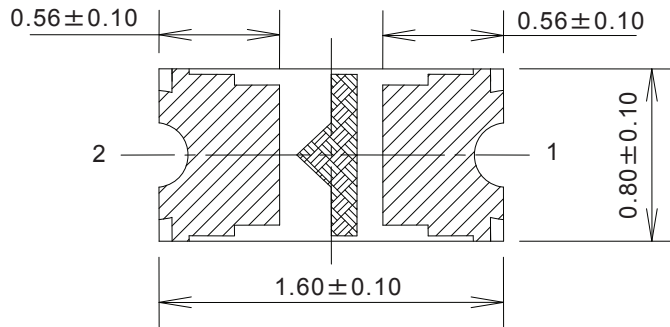
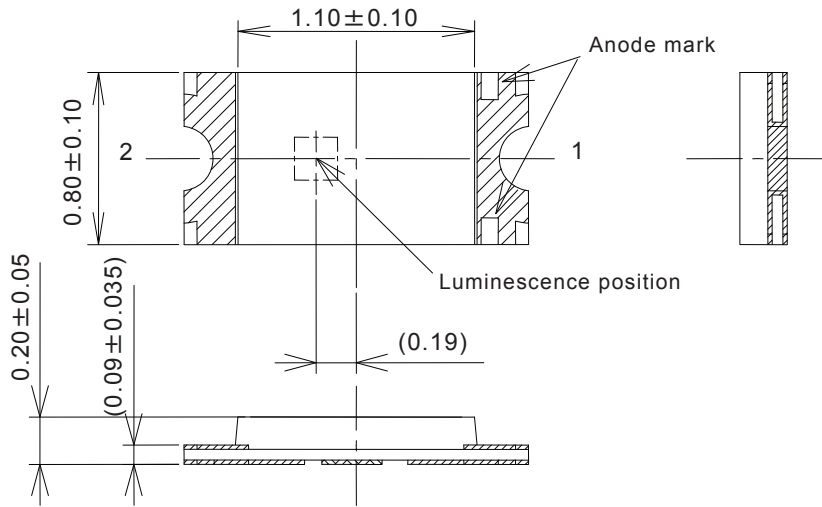
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *1	I_O	$I_F = 5 \text{ mA}$	11.5	17.5	47.3	mcd
Reverse current	I_R	$V_R = 4 \text{ V}$			100	μA
Forward voltage	V_F	$I_F = 5 \text{ mA}$		1.95	2.30	V
Peak emission wavelength	λ_p	$I_F = 5 \text{ mA}$		630		nm
Dominant emission wavelength *2	λ_d	$I_F = 5 \text{ mA}$	615	620	627	nm
Spectral half band width	$\Delta\lambda$	$I_F = 5 \text{ mA}$		13		nm

Note) *1: Measurement tolerance: $\pm 20\%$

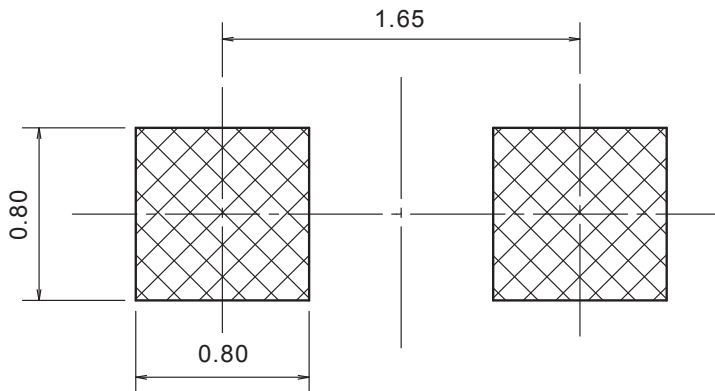
*2: Measurement tolerance: $\pm 2 \text{ nm}$



■ Package (Unit: mm)



Recommended Land Layout



(Note1) Electrode projection is not included in the package dimensions.

(Note2) About solder thickness, please examine the products yourself completely.

(Recommended thickness : $t=0.10$ mm~ 0.15 mm)

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